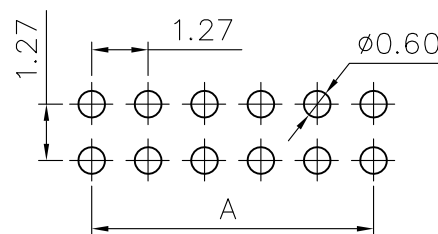
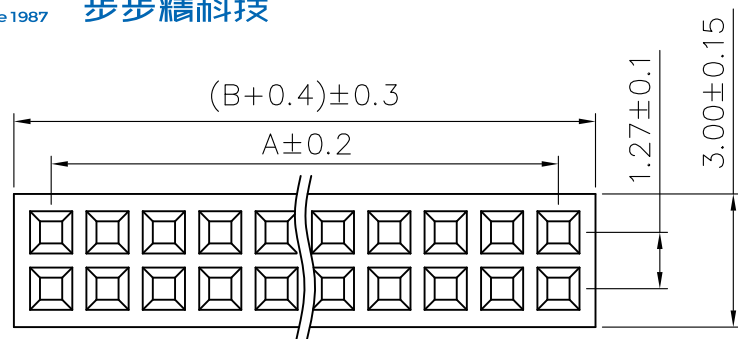
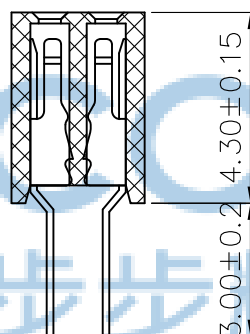
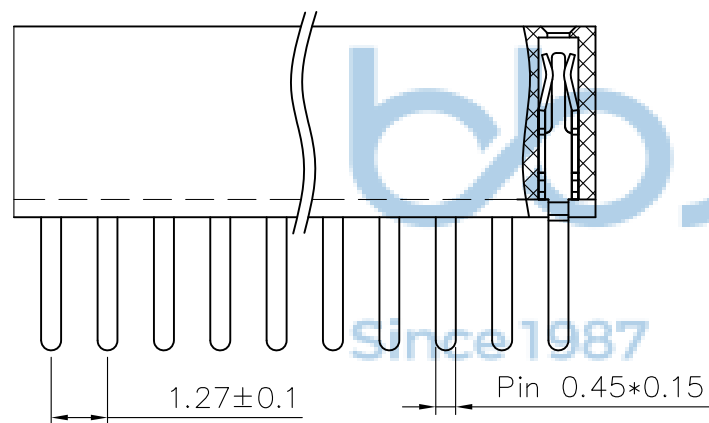


REV.	ECN NO	CONTENT	DATE	ENGINEER
A0			2023 20/04	



RECOMMEND P. C. B LAYOUT

PCB TOLERANCE: ± 0.05 (TOP VIEW)

No. of	DIM. A	DIM. B	No. of	DIM. A	DIM. B	No. of	DIM. A	DIM. B	No. of	DIM. A	DIM. B	No. of	DIM. A	DIM. B
1	—	—	11	12.70	13.97	21	25.40	26.67	31	38.10	39.37	41	50.80	52.07
2	1.27	2.54	12	13.97	15.24	22	26.67	27.94	32	39.37	40.64	42	52.07	53.34
3	2.54	3.81	13	15.24	16.51	23	27.94	29.21	33	40.64	41.91	43	53.34	54.61
4	3.81	5.08	14	16.51	17.78	24	29.21	30.48	34	41.91	43.18	44	54.61	55.88
5	5.08	6.35	15	17.78	19.05	25	30.48	31.75	35	43.18	44.45	45	55.88	57.15
6	6.35	7.62	16	19.05	20.32	26	31.75	33.02	36	44.45	45.72	46	57.15	58.42
7	7.62	8.89	17	20.32	21.59	27	33.02	34.29	37	45.72	46.99	47	58.42	59.69
8	8.89	10.16	18	21.59	22.86	28	34.29	35.56	38	46.99	48.26	48	59.69	60.96
9	10.16	11.43	19	22.86	24.13	29	35.56	36.83	39	48.26	49.53	49	60.96	62.23
10	11.43	12.70	20	24.13	25.40	30	36.83	38.10	40	49.53	50.80	50	62.23	63.50

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深圳市步步精科技有限公司

.X: ± 0.38	X*: $\pm 3^*$
.XX: ± 0.25	.X*: $\pm 2^*$
.XXX: ± 0.13	.XX*: $\pm 1^*$

$$\begin{array}{l} X^*: \pm 3^* \\ .X^*: \pm 2^* \\ .XX^*: \pm 1^* \end{array}$$

NAME: 排母 1.27FH H4.3 2x5P 180度 U型 PC3.0 6T

APPD.	JM_Zheng	23/05
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ng 23/05

2		PJ. NO.: FH.03.12-21-3002
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CHKD.	TSP	23/05
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23/05

2	SIZE: A4	DRW NO.:
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DR.	LYX	23/05
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23/05'

FINISH: SEE NOTES		MAT'L.: SEE NOTE	
SCALE: N/A	REV: A3	UNIT: mm	PAGE: 1

ERA	ERA	19/00
	6	

SCALE: N/A	REV.: AS	UNIT: mm	PAGE: 1
7			8